

# SOT1129-3

plastic, ball grid array; 324 bumps; 1.0 mm pitch; 23 mm x 23 mm x 1.95 mm body

13 December 2016

Package information

## 1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA
Package type industry code	BGA324
Package style descriptive code	BGA (ball grid array)
Package body material type	P (plastic)
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	6-7-2016
Manufacturer package code	98ASS23840W

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		-	-	23	-	mm
E	package width		-	-	23	-	mm
A	seated height		1.95	-	2.25	2.55	mm
A <sub>2</sub>	package height		0.5	-	0.6	0.7	mm
e	nominal pitch		-	-	1	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	324	-	



2. Package outline

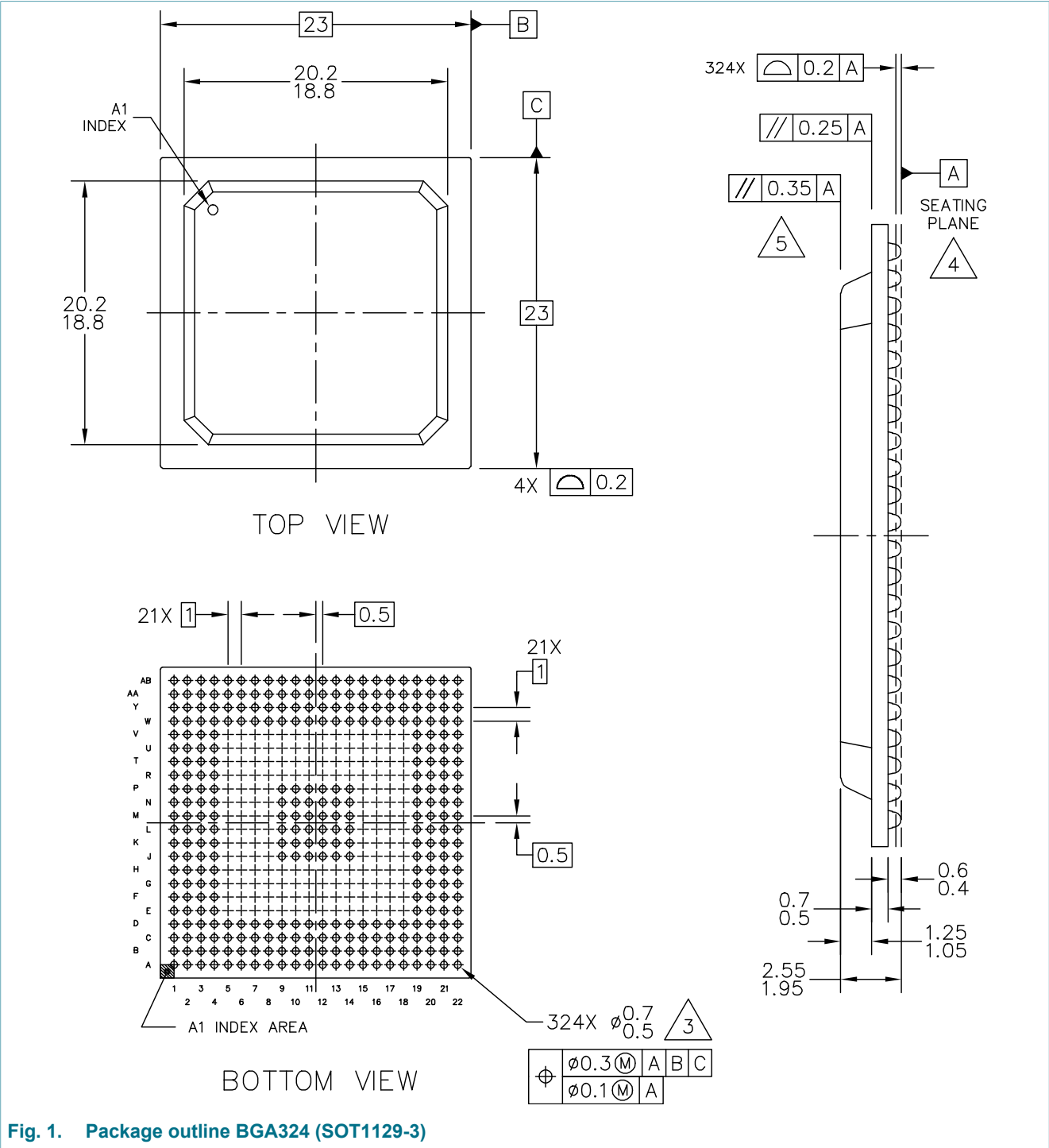


Fig. 1. Package outline BGA324 (SOT1129-3)

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## NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

6. PACKAGE CODES:

5241: 2 LAYER 324 PBGA

5366: 4 LAYER 324 TEPBGA PGE

**Fig. 2. Package outline note BGA324 (SOT1129-3)**

### 3. Legal information

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